

HEF4060B

14-stage ripple-carry binary counter/divider and oscillator

Rev. 7 — 16 November 2011

Product data sheet

1. General description

The HEF4060B is a 14-stage ripple-carry binary counter/divider and oscillator with three oscillator terminals (RS, REXT and CEXT), ten buffered outputs (Q3 to Q9 and Q11 to Q13) and an overriding asynchronous master reset input (MR).

The oscillator configuration allows design of either RC or crystal oscillator circuits. The oscillator may be replaced by an external clock signal at input RS. The clock input's Schmitt-trigger action makes it highly tolerant to slower clock rise and fall times. The counter advances on the negative-going transition of RS. A HIGH level on MR resets the counter (Q3 to Q9 and Q11 to Q13 = LOW), independent of other input conditions.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD} , V_{SS} , or another input.

2. Features and benefits

- Tolerant of slow clock rise and fall times
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Inputs and outputs are protected against electrostatic effects
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

3. Ordering information

Table 1. Ordering information

All types operate from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$.

| Type number | Package | | Version |
|-------------|---------|--|----------|
| | Name | Description | |
| HEF4060BP | DIP16 | plastic dual in-line package; 16 leads (300 mil) | SOT38-4 |
| HEF4060BT | SO16 | plastic small outline package; 16 leads; body width 3.9 mm | SOT109-1 |



4. Functional diagram

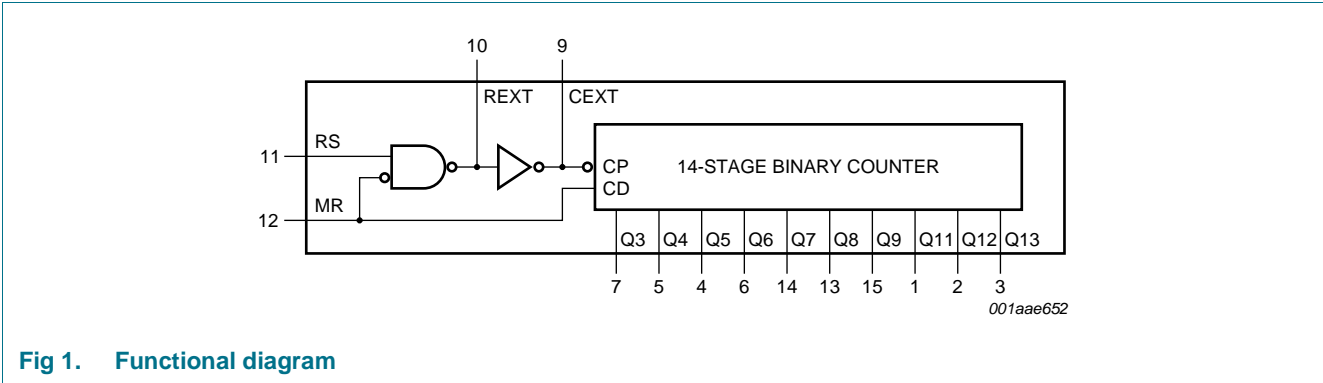


Fig 1. Functional diagram

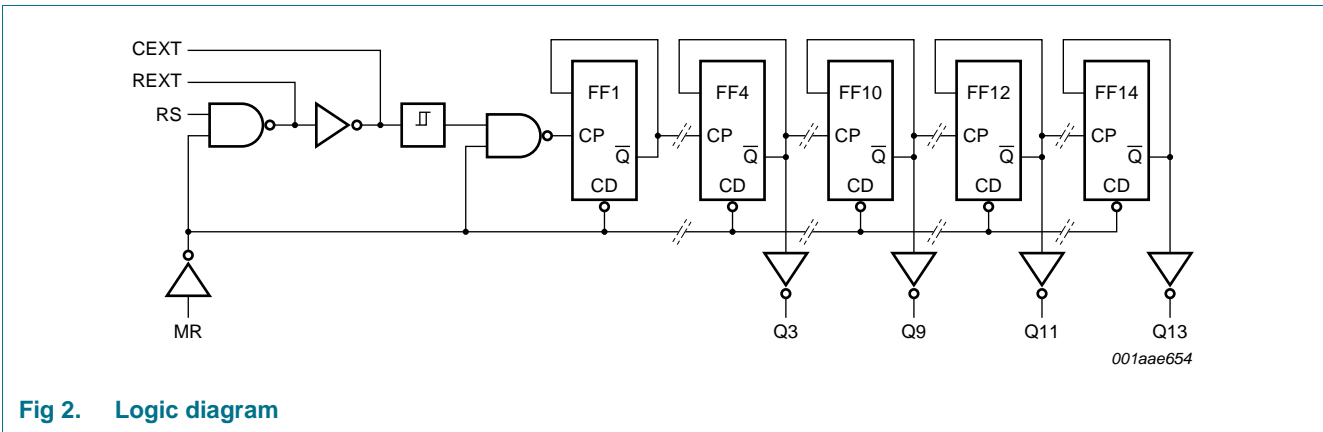


Fig 2. Logic diagram

5. Pinning information

5.1 Pinning

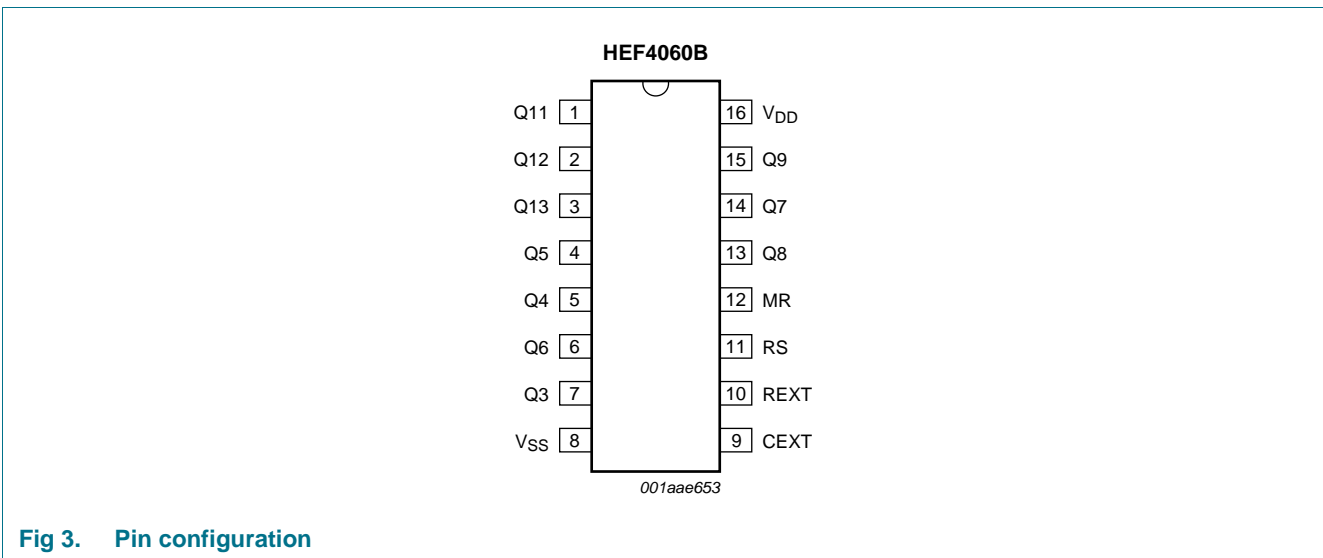


Fig 3. Pin configuration

5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|-----------------|------------------------|-------------------------------|
| Q11 to Q13 | 1, 2, 3 | counter output |
| Q3 to Q9 | 7, 5, 4, 6, 14, 13, 15 | counter output |
| V _{SS} | 8 | ground supply voltage |
| CEXT | 9 | external capacitor connection |
| REXT | 10 | oscillator pin |
| RS | 11 | clock input/oscillator pin |
| MR | 12 | master reset |
| V _{DD} | 16 | supply voltage |

6. Functional description

Table 3. Function table^[1]

| Input | | Output |
|-------|----|-------------------------|
| RS | MR | Q3 to Q9 and Q11 to Q13 |
| ↑ | L | no change |
| ↓ | L | count |
| X | H | L |

[1] H = HIGH voltage level; L = LOW voltage level; ↑ = LOW-to-HIGH clock transition; ↓ HIGH-to-LOW clock transition.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit | |
|------------------|-------------------------|---|------|-----------------------|------|----|
| V _{DD} | supply voltage | | -0.5 | +18 | V | |
| I _{IK} | input clamping current | V _I < -0.5 V or V _I > V _{DD} + 0.5 V | - | ±10 | mA | |
| V _I | input voltage | | -0.5 | V _{DD} + 0.5 | V | |
| I _{OK} | output clamping current | V _O < -0.5 V or V _O > V _{DD} + 0.5 V | - | ±10 | mA | |
| I _{I/O} | input/output current | | - | ±10 | mA | |
| I _{DD} | supply current | | - | 50 | mA | |
| T _{stg} | storage temperature | | -65 | +150 | °C | |
| T _{amb} | ambient temperature | | -40 | +85 | °C | |
| P _{tot} | total power dissipation | T _{amb} -40 °C to +85 °C | | | | |
| | | DIP16 package | [1] | - | 750 | mW |
| | | SO16 package | [2] | - | 500 | mW |
| P | power dissipation | per output | - | 100 | mW | |

[1] For DIP16 package: P_{tot} derates linearly with 12 mW/K above 70 °C.

[2] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---------------------|-------------------------------------|------------------------|-----|-----|----------|-----------------|
| V_{DD} | supply voltage | | 3 | - | 15 | V |
| V_I | input voltage | | 0 | - | V_{DD} | V |
| T_{amb} | ambient temperature | in free air | -40 | - | +85 | °C |
| $\Delta t/\Delta V$ | input transition rise and fall rate | input MR | | | | |
| | | $V_{DD} = 5\text{ V}$ | - | - | 3.75 | $\mu\text{s/V}$ |
| | | $V_{DD} = 10\text{ V}$ | - | - | 0.5 | $\mu\text{s/V}$ |
| | | $V_{DD} = 15\text{ V}$ | - | - | 0.08 | $\mu\text{s/V}$ |

9. Static characteristics

Table 6. Static characteristics

$V_{SS} = 0\text{ V}$; $V_I = V_{SS}$ or V_{DD} unless otherwise specified.

| Symbol | Parameter | Conditions | V_{DD} | $T_{amb} = -40\text{ °C}$ | | $T_{amb} = 25\text{ °C}$ | | $T_{amb} = 85\text{ °C}$ | | Unit |
|----------|---------------------------|--------------------------|----------|---------------------------|-----------|--------------------------|-----------|--------------------------|-----------|---------------|
| | | | | Min | Max | Min | Max | Min | Max | |
| V_{IH} | HIGH-level input voltage | $ I_O < 1\ \mu\text{A}$ | 5 V | 3.5 | - | 3.5 | - | 3.5 | - | V |
| | | | 10 V | 7.0 | - | 7.0 | - | 7.0 | - | V |
| | | | 15 V | 11.0 | - | 11.0 | - | 11.0 | - | V |
| V_{IL} | LOW-level input voltage | $ I_O < 1\ \mu\text{A}$ | 5 V | - | 1.5 | - | 1.5 | - | 1.5 | V |
| | | | 10 V | - | 3.0 | - | 3.0 | - | 3.0 | V |
| | | | 15 V | - | 4.0 | - | 4.0 | - | 4.0 | V |
| V_{OH} | HIGH-level output voltage | $ I_O < 1\ \mu\text{A}$ | 5 V | 4.95 | - | 4.95 | - | 4.95 | - | V |
| | | | 10 V | 9.95 | - | 9.95 | - | 9.95 | - | V |
| | | | 15 V | 14.95 | - | 14.95 | - | 14.95 | - | V |
| V_{OL} | LOW-level output voltage | $ I_O < 1\ \mu\text{A}$ | 5 V | - | 0.05 | - | 0.05 | - | 0.05 | V |
| | | | 10 V | - | 0.05 | - | 0.05 | - | 0.05 | V |
| | | | 15 V | - | 0.05 | - | 0.05 | - | 0.05 | V |
| I_{OH} | HIGH-level output current | $V_O = 2.5\text{ V}$ | 5 V | - | -1.7 | - | -1.4 | - | -1.1 | mA |
| | | $V_O = 4.6\text{ V}$ | 5 V | - | -0.52 | - | -0.44 | - | -0.36 | mA |
| | | $V_O = 9.5\text{ V}$ | 10 V | - | -1.3 | - | -1.1 | - | -0.9 | mA |
| | | $V_O = 13.5\text{ V}$ | 15 V | - | -3.6 | - | -3.0 | - | -2.4 | mA |
| I_{OL} | LOW-level output current | $V_O = 0.4\text{ V}$ | 5 V | 0.52 | - | 0.44 | - | 0.36 | - | mA |
| | | $V_O = 0.5\text{ V}$ | 10 V | 1.3 | - | 1.1 | - | 0.9 | - | mA |
| | | $V_O = 1.5\text{ V}$ | 15 V | 3.6 | - | 3.0 | - | 2.4 | - | mA |
| I_I | input leakage current | | 15 V | - | ± 0.3 | - | ± 0.3 | - | ± 1.0 | μA |
| I_{DD} | supply current | $I_O = 0\text{ A}$ | 5 V | - | 20 | - | 20 | - | 150 | μA |
| | | | 10 V | - | 40 | - | 40 | - | 300 | μA |
| | | | 15 V | - | 80 | - | 80 | - | 600 | μA |
| C_I | input capacitance | | - | - | - | - | 7.5 | - | - | pF |

10. Dynamic characteristics

Table 7. Dynamic characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{SS} = 0\text{ V}$; $C_L = 50\text{ pF}$; $t_r = t_f \leq 20\text{ ns}$; unless otherwise specified.

| Symbol | Parameter | Conditions | V_{DD} | Extrapolation formula ^[1] | Min | Typ | Max | Unit |
|-----------|-------------------|---|--------------------|---|-----|-----|-----|------|
| t_{pd} | propagation delay | RS \rightarrow Q3; see Figure 4 | 5 V ^[2] | $183\text{ ns} + (0.55\text{ ns/pF}) C_L$ | - | 210 | 420 | ns |
| | | | 10 V | $69\text{ ns} + (0.23\text{ ns/pF}) C_L$ | - | 80 | 160 | ns |
| | | | 15 V | $42\text{ ns} + (0.16\text{ ns/pF}) C_L$ | - | 50 | 100 | ns |
| | | Qn \rightarrow Qn + 1; see Figure 4 | 5 V | - | - | 25 | 50 | ns |
| | | | 10 V | - | - | 10 | 20 | ns |
| | | | 15 V | - | - | 6 | 12 | ns |
| | | MR \rightarrow Qn; HIGH to LOW see Figure 4 | 5 V | $73\text{ ns} + (0.55\text{ ns/pF}) C_L$ | - | 100 | 200 | ns |
| | | | 10 V | $29\text{ ns} + (0.23\text{ ns/pF}) C_L$ | - | 40 | 80 | ns |
| | | | 15 V | $22\text{ ns} + (0.16\text{ ns/pF}) C_L$ | - | 30 | 60 | ns |
| t_t | transition time | see Figure 4 | 5 V ^[3] | $10\text{ ns} + (1.00\text{ ns/pF}) C_L$ | - | 60 | 120 | ns |
| | | | 10 V | $9\text{ ns} + (0.42\text{ ns/pF}) C_L$ | - | 30 | 60 | ns |
| | | | 15 V | $6\text{ ns} + (0.28\text{ ns/pF}) C_L$ | - | 20 | 40 | ns |
| t_w | pulse width | minimum width; RS HIGH; see Figure 4 | 5 V | - | 120 | 60 | - | ns |
| | | | 10 V | - | 50 | 25 | - | ns |
| | | | 15 V | - | 30 | 15 | - | ns |
| | | minimum width; MR HIGH; see Figure 4 | 5 V | - | 50 | 25 | - | ns |
| | | | 10 V | - | 30 | 15 | - | ns |
| | | | 15 V | - | 20 | 10 | - | ns |
| t_{rec} | recovery time | input MR; see Figure 4 | 5 V | - | 160 | 80 | - | ns |
| | | | 10 V | - | 80 | 40 | - | ns |
| | | | 15 V | - | 60 | 30 | - | ns |
| f_{max} | maximum frequency | input RS; see Figure 4 | 5 V | - | 4 | 8 | - | MHz |
| | | | 10 V | - | 10 | 20 | - | MHz |
| | | | 15 V | - | 15 | 30 | - | MHz |

[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown (C_L in pF).

[2] t_{pd} is the same as t_{PHL} and t_{PLH} .

[3] t_t is the same as t_{THL} and t_{TLH} .

Table 8. Power dissipation

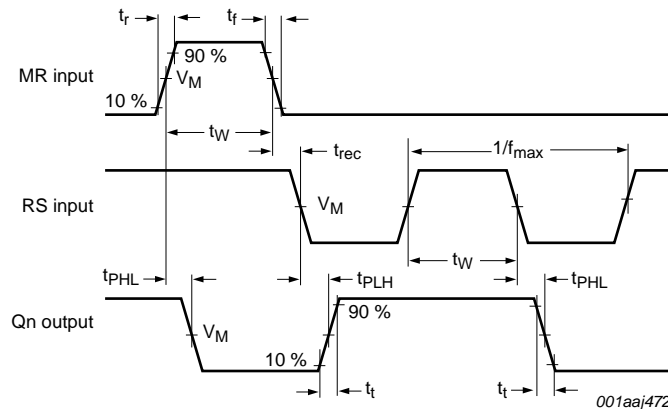
Dynamic power dissipation P_D and total power dissipation P_{tot} can be calculated from the formulas shown. $T_{amb} = 25\text{ }^\circ\text{C}$.

| Symbol | Parameter | Conditions | V_{DD} | Typical formula for P_D and P_{tot} (μW) ^[1] |
|-----------|---------------------------|-----------------------------------|----------|--|
| P_D | dynamic power dissipation | per device | 5 V | $P_D = 700 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ |
| | | | 10 V | $P_D = 3300 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ |
| | | | 15 V | $P_D = 8900 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ |
| P_{tot} | total power dissipation | when using the on-chip oscillator | 5 V | $P_{tot} = 700 \times f_{osc} + \Sigma(f_o \times C_L) \times V_{DD}^2 + 2 \times C_t \times V_{DD}^2 \times f_{osc} + 690 \times V_{DD}$ |
| | | | 10 V | $P_{tot} = 3300 \times f_{osc} + \Sigma(f_o \times C_L) \times V_{DD}^2 + 2 \times C_t \times V_{DD}^2 \times f_{osc} + 6900 \times V_{DD}$ |
| | | | 15 V | $P_{tot} = 8900 \times f_{osc} + \Sigma(f_o \times C_L) \times V_{DD}^2 + 2 \times C_t \times V_{DD}^2 \times f_{osc} + 22000 \times V_{DD}$ |

[1] Where:

- f_i = input frequency in MHz; f_o = output frequency in MHz;
- C_L = output load capacitance in pF;
- V_{DD} = supply voltage in V;
- $\Sigma(f_o \times C_L)$ = sum of the outputs;
- C_t = timing capacitance (pF);
- f_{osc} = oscillator frequency (MHz).

11. Waveforms

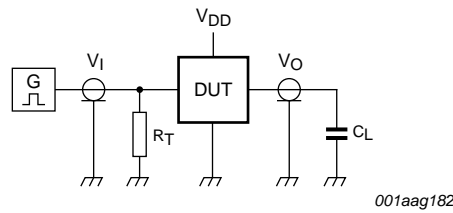


Measurement points are given in [Table 9](#).

Fig 4. Waveforms showing propagation delays for MR to Qn and \overline{CP} to Q0, minimum MR, and \overline{CP} pulse widths

Table 9. Measurement points

| Supply voltage | Input | Output |
|----------------|-------------|-------------|
| V_{DD} | V_M | V_M |
| 5 V to 15 V | $0.5V_{DD}$ | $0.5V_{DD}$ |



Test data is given in [Table 10](#).

Definitions for test circuit:

DUT = Device Under Test;

C_L = load capacitance including jig and probe capacitance;

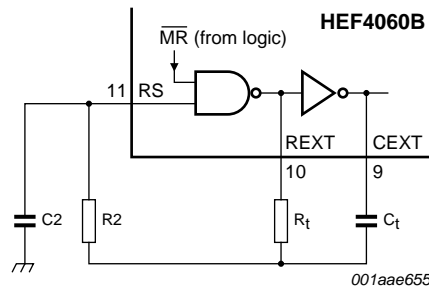
R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig 5. Test circuit for switching times

Table 10. Measurement point and test data

| Supply voltage | Input | | Load |
|----------------|----------------------|--------------|-------|
| V_{DD} | V_I | t_r, t_f | C_L |
| 5 V to 15 V | V_{SS} or V_{DD} | ≤ 20 ns | 50 pF |

12. RC oscillator



Typical formula for oscillator frequency:
$$f_{osc} = \frac{1}{2.3 \times R_t \times C_t}$$

Fig 6. External component connection for RC oscillator

12.1 Timing component limitations

The oscillator frequency is mainly determined by $R_t \times C_t$, provided $R_t \ll R_2$ and $R_2 \times C_2 \ll R_t \times C_t$. The influence of the forward voltage across the input protection diodes on the frequency is minimized by R_2 . The stray capacitance C_2 should be kept as small as possible. In consideration of accuracy, C_t must be larger than the inherent stray capacitance. R_t must be larger than the LOCMOS (Local Oxidation Complementary Metal-Oxide Semiconductor) 'ON' resistance in series with it, which typically is 500 Ω at $V_{DD} = 5$ V, 300 Ω at $V_{DD} = 10$ V and 200 Ω at $V_{DD} = 15$ V.

The recommended values for these components to maintain agreement with the typical oscillation formula are:

$$C_t \geq 100 \text{ pF, up to any practical value,}$$

$$10 \text{ k}\Omega \leq R_t \leq 1 \text{ M}\Omega.$$

12.2 Typical crystal oscillator circuit

In [Figure 7](#), R2 is the power limiting resistor. For starting and maintaining oscillation a minimum transconductance is necessary.

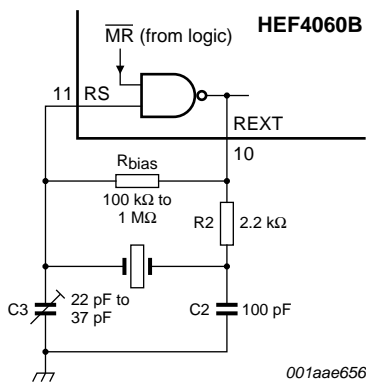
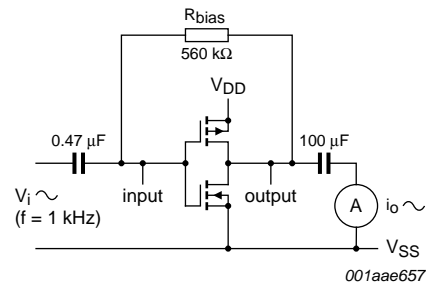
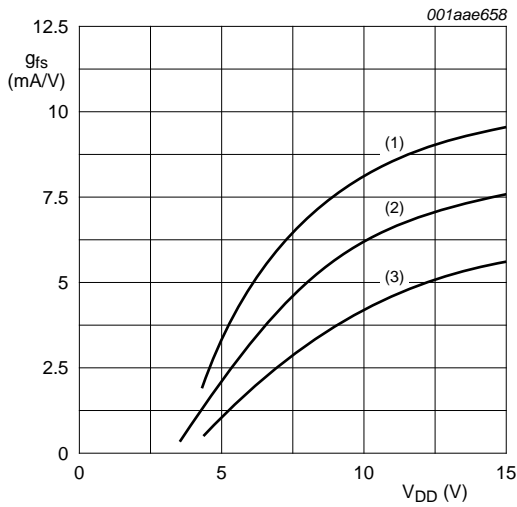


Fig 7. External component connection for crystal oscillator



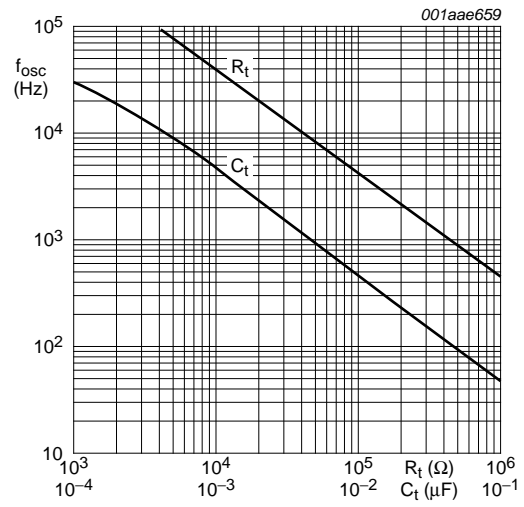
$g_{fs} = di_o/dv_i$ at v_o is constant (see also [Figure 9](#));
MR = LOW.

Fig 8. Test setup for measuring forward transconductance (g_{fs})



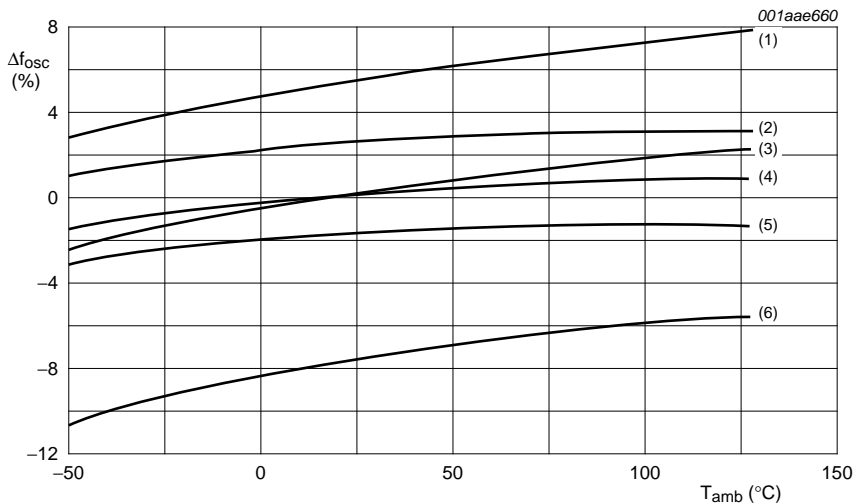
$T_{amb} = 25\text{ }^{\circ}\text{C}$.
 (1) Average + 2 σ .
 (2) Average.
 (3) Average - 2 σ .
 Where ' σ ' is the observed standard deviation.

Fig 9. Typical forward transconductance g_{fs} as a function of the supply voltage



C_t curve at $R_t = 100\text{ k}\Omega$; $R_2 = 470\text{ k}\Omega$.
 R_t curve at $C_t = 1\text{ nF}$; $R_2 = 5 R_t$.
 $V_{DD} = 5\text{ V to } 15\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Fig 10. RC oscillator frequency as a function of R_t and C_t



Lines (1) and (2): $V_{DD} = 15\text{ V}$.
 Lines (3) and (4): $V_{DD} = 10\text{ V}$.
 Lines (5) and (6): $V_{DD} = 5\text{ V}$.
 Lines (1), (3), (6): $R_t = 100\text{ k}\Omega$; $C_t = 1\text{ nF}$; $R_2 = 0\text{ W}$.
 Lines (2), (4), (5): $R_t = 100\text{ k}\Omega$; $C_t = 1\text{ nF}$; $R_2 = 300\text{ k}\Omega$.
 Referenced at: f_{osc} at $T_{amb} = 25\text{ }^{\circ}\text{C}$ and $V_{DD} = 10\text{ V}$.

Fig 11. Oscillator frequency deviation (Δf_{osc}) as a function of ambient temperature

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

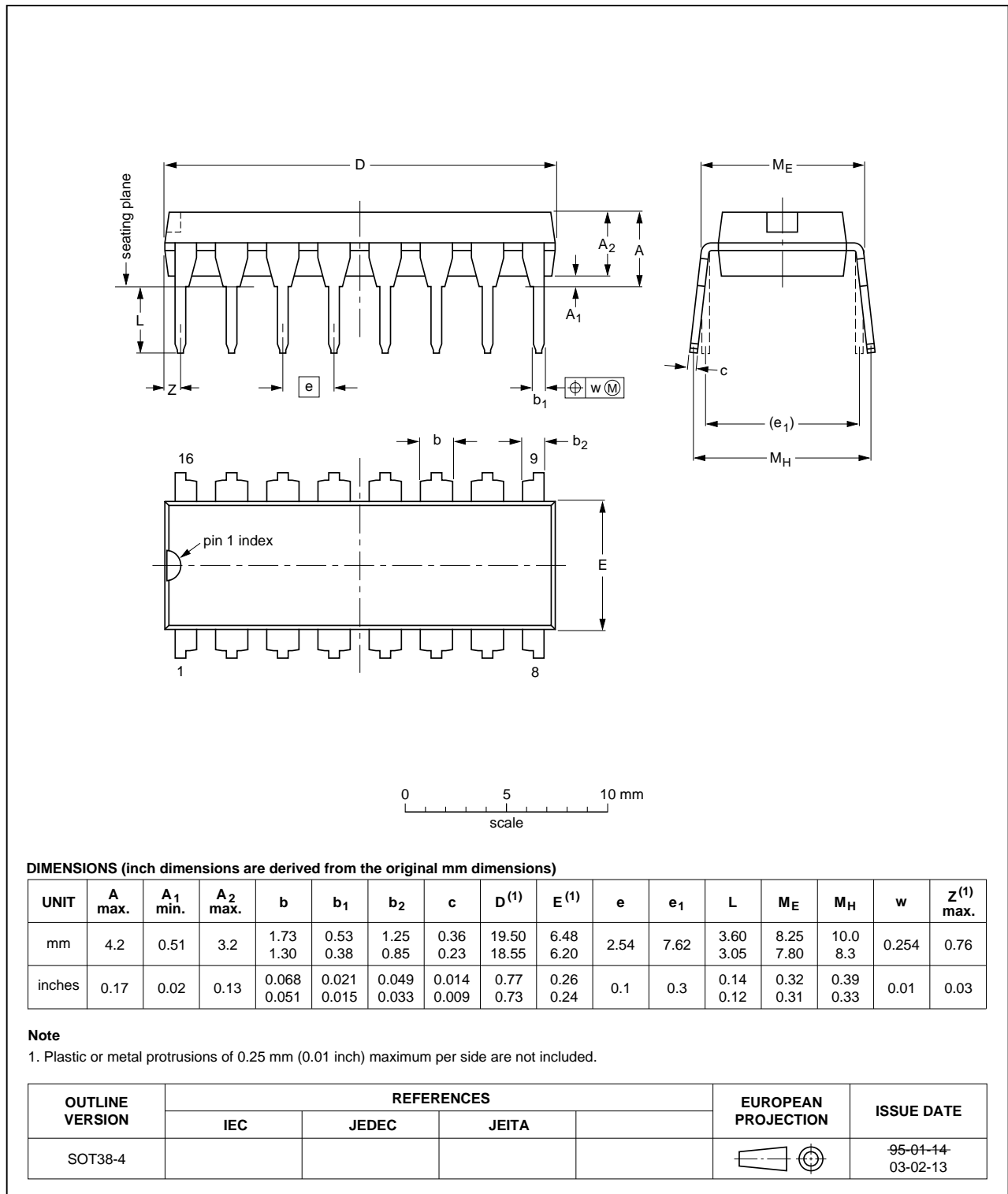


Fig 12. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

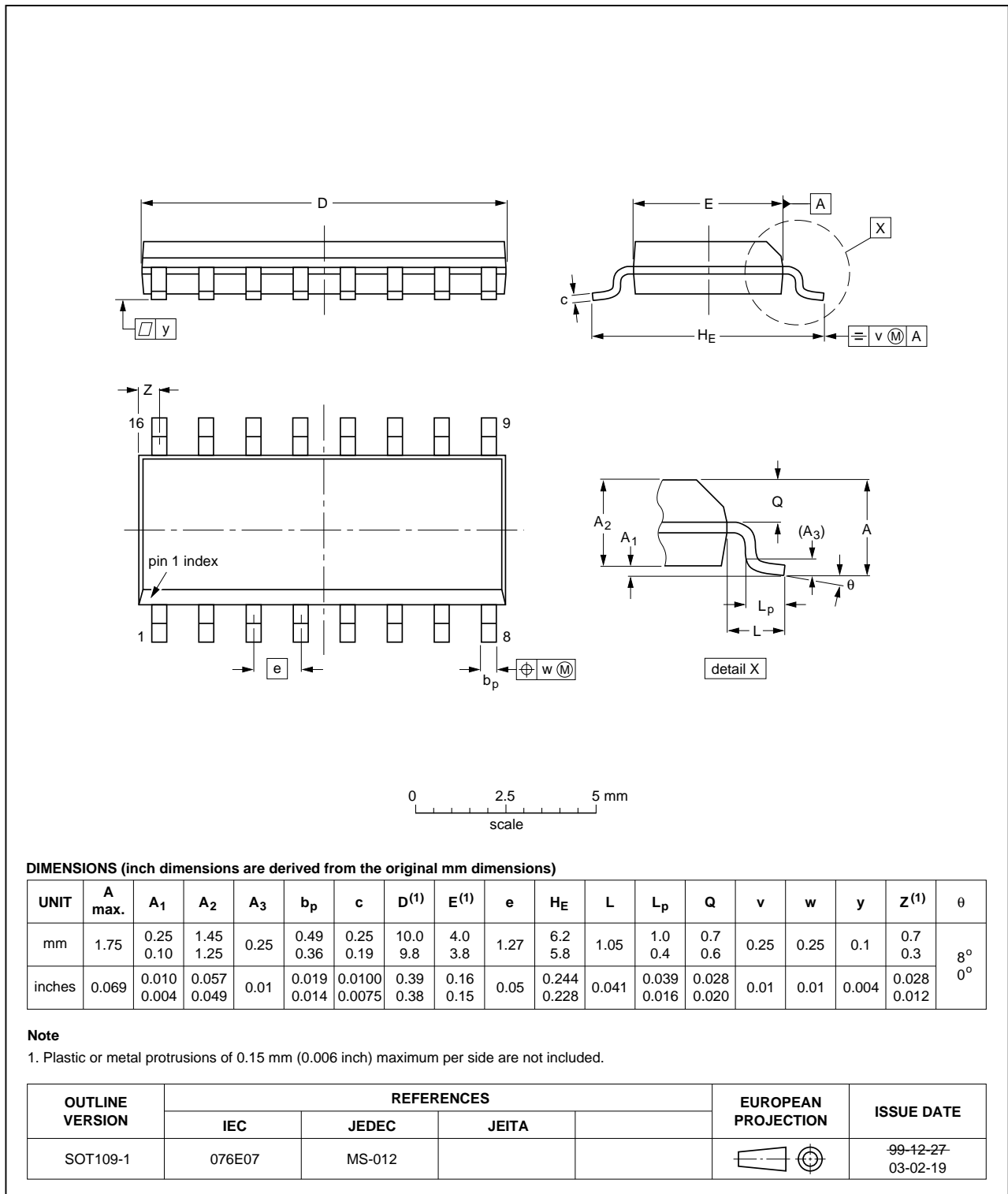


Fig 13. Package outline SOT109-1 (SO16)

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|------------------|--------------|--|---------------|------------------|
| HEF4060B v.7 | 20111116 | Product data sheet | - | HEF4060B v.6 |
| Modifications: | | <ul style="list-style-type: none">• Legal pages updated.• Changes in “General description” and “Features and benefits”.• Section “Applications” removed. | | |
| HEF4060B v.6 | 20110511 | Product data sheet | - | HEF4060B v.5 |
| HEF4060B v.5 | 20091127 | Product data sheet | - | HEF4060B v.4 |
| HEF4060B v.4 | 20090817 | Product data sheet | - | HEF4060B_CNV v.3 |
| HEF4060B_CNV v.3 | 19950101 | Product specification | - | HEF4060B_CNV v.2 |
| HEF4060B_CNV v.2 | 19950101 | Product specification | - | - |

15. Legal information

15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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